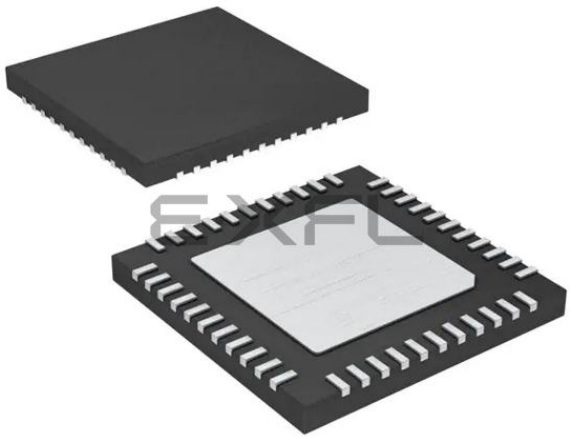

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, HLVD, I²S, POR, PWM, WDT
Number of I/O	34
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx254f128d-i-ml

TABLE 1: PIC32MX1XX 28/44-PIN XLP (GENERAL PURPOSE) FAMILY FEATURES

Device	Pins	Program Memory (KB)(1)	Data Memory (KB)	Remappable Peripherals					Analog Comparators	I²C™	PMP	DMA Channels (Programmable/Dedicated)	CTMU	10-bit 1 Msps ADC (Channels)	RTCC	I/O Pins	JTAG	VBAT	Packages
				Remappable Pins	Timers(2)/Capture/ Compare/PWM	UART	SPI/I²S	External Interrupts(3)											
PIC32MX154F128B	28	128+12	32	20	5/5/5/5	2	2	5	3	2	Y	4/2	Y	10	Y	21	Y	N	SOIC, QFN
PIC32MX154F128D	44			30										13		35		N	TQFP, QFN
PIC32MX155F128B	28			19										9		20		Y	SOIC, QFN
PIC32MX155F128D	44			29										12		35		Y	TQFP, QFN
PIC32MX174F256B	28	256+12	64	20	5/5/5/5	2	2	5	3	2	Y	4/2	Y	10	Y	21	Y	N	SOIC, QFN
PIC32MX174F256D	44			30										13		35		N	TQFP, QFN
PIC32MX175F256B	28			19										9		20		Y	SOIC, QFN
PIC32MX175F256D	44			29										12		35		Y	TQFP, QFN

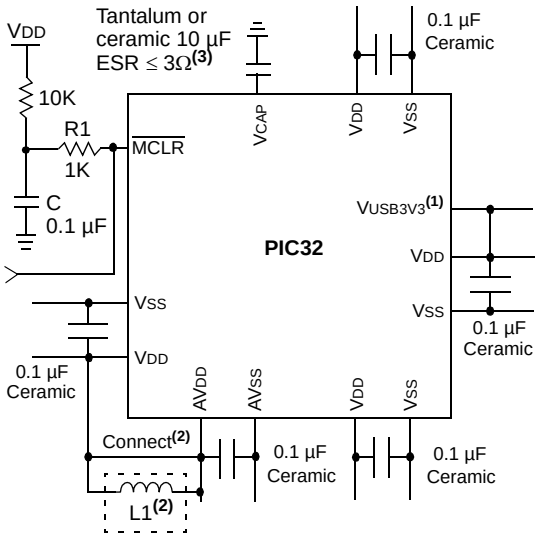
Note 1: This device features 12 KB of Boot Flash memory.
2: Four out of five timers are remappable.
3: Four out of five external interrupts are remappable.

TABLE 2: PIC32MX2XX 28/44-PIN XLP (USB) FAMILY FEATURES

Device	Pins	Program Memory (KB)(1)	Data Memory (KB)	Remappable Peripherals					Analog Comparators	USB On-The-Go (OTG)	I²C™	PMP	DMA Channels (Programmable/Dedicated)	CTMU	10-bit 1 Msps ADC (Channels)	RTCC	I/O Pins	JTAG	VBAT	Packages
				Remappable Pins	Timers(2)/Capture/ Compare/PWM	UART	SPI/I²S	External Interrupts(3)												
PIC32MX254F128B	28	128+12	32	17	5/5/5/5	2	2	5	3	Y	2	Y	4/2	Y	9	Y	17	Y	N	SOIC, QFN
PIC32MX254F128D	44			29											13		35		N	TQFP, QFN
PIC32MX255F128B	28			16											8		16		Y	SOIC, QFN
PIC32MX255F128D	44			28											12		35		Y	TQFP, QFN
PIC32MX274F256B	28	256+12	64	17	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	9	Y	17	Y	N	SOIC, QFN
PIC32MX274F256D	44			29											13		35		N	TQFP, QFN
PIC32MX275F256B	28			16											8		16		Y	SOIC, QFN
PIC32MX275F256D	44			28											12		35		Y	TQFP, QFN

Note 1: This device features 12 KB of Boot Flash memory.
2: Four out of five timers are remappable.
3: Four out of five external interrupts are remappable.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: If the USB module is not used, this pin must be connected to VDD.

2: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 3Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

1: Aluminum or electrolytic capacitors should not be used. ESR ≤ 3Ω from -40ºC to 125ºC @ SYSCLK frequency (i.e., MIPS).

2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (3 ohm) capacitor is required on the VCAP pin, which is used to stabilize the internal voltage regulator output. The VCAP pin must not be connected to VDD, and must have a CEFC capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **33.0 "Electrical Characteristics"** for additional information on CEFC specifications.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

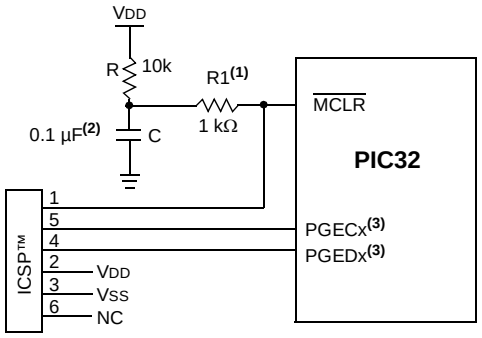
- Device Reset
- Device programming and debugging

Pulling The MCLR pin low generates a device Reset. Figure 2-2 illustrates a typical MCLR circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components illustrated in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: 470Ω ≤ R1 ≤ 1Ω will limit any current flowing into MCLR from the external capacitor C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met without interfering with the Debug/Programmer tools.

2: The capacitor can be sized to prevent unintentional Resets from brief glitches or to extend the device Reset period during POR.

3: No pull-ups or bypass capacitors are allowed on active debug/program PGECx/PGEDx pins.

REGISTER 7-4: IFSx: INTERRUPT FLAG STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS31	IFS30	IFS29	IFS28	IFS27	IFS26	IFS25	IFS24
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS23	IFS22	IFS21	IFS20	IFS19	IFS18	IFS17	IFS16
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS15	IFS14	IFS13	IFS12	IFS11	IFS10	IFS09	IFS08
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS07	IFS06	IFS05	IFS04	IFS03	IFS02	IFS01	IFS00

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **IFS31-IFS00:** Interrupt Flag Status bits
1 = Interrupt request has occurred
0 = No interrupt request has occurred

Note: This register represents a generic definition of the IFSx register. Refer to Table 7-1 for the exact bit definitions.

REGISTER 7-5: IECx: INTERRUPT ENABLE CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC31	IEC30	IEC29	IEC28	IEC27	IEC26	IEC25	IEC24
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC23	IEC22	IEC21	IEC20	IEC19	IEC18	IEC17	IEC16
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC15	IEC14	IEC13	IEC12	IEC11	IEC10	IEC09	IEC08
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC07	IEC06	IEC05	IEC04	IEC03	IEC02	IEC01	IEC00

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **IEC31-IEC00:** Interrupt Enable bits
1 = Interrupt is enabled
0 = Interrupt is disabled

Note: This register represents a generic definition of the IECx register. Refer to Table 7-1 for the exact bit definitions.

9.0 DIRECT MEMORY ACCESS (DMA) CONTROLLER

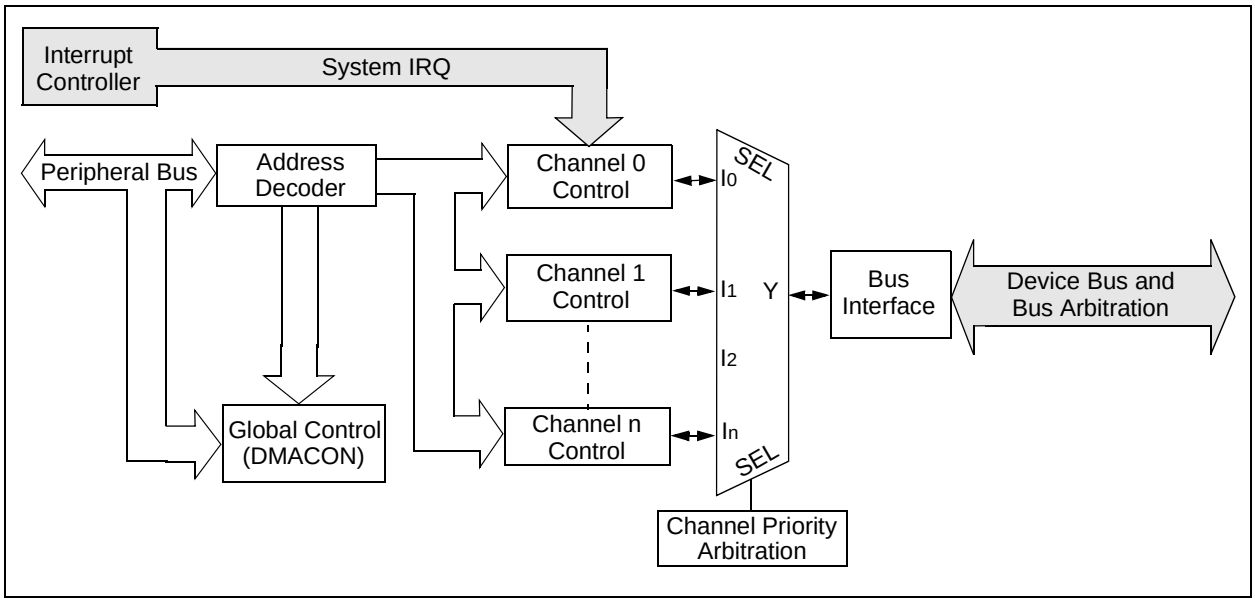
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/44-pin XLP Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 31. "Direct Memory Access (DMA) Controller"** (DS60001117), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 Direct Memory Access (DMA) controller is a bus master module useful for data transfers between different devices without CPU intervention. The source and destination of a DMA transfer can be any of the memory mapped modules existent in the PIC32, such as Peripheral Bus devices: SPI, UART, PMP, etc., or memory itself. Figure 9-1 show a block diagram of the DMA Controller module.

The DMA Controller module has the following key features:

- Four identical channels, each featuring:
  - Auto-increment source and destination address registers
  - Source and destination pointers
  - Memory to memory and memory to peripheral transfers
- Automatic word-size detection:
  - Transfer granularity, down to byte level
  - Bytes need not be word-aligned at source and destination
- Fixed priority channel arbitration
- Flexible DMA channel operating modes:
  - Manual (software) or automatic (interrupt) DMA requests
  - One-Shot or Auto-Repeat Block Transfer modes
  - Channel-to-channel chaining
- Flexible DMA requests:
  - A DMA request can be selected from any of the peripheral interrupt sources
  - Each channel can select any (appropriate) observable interrupt as its DMA request source
  - A DMA transfer abort can be selected from any of the peripheral interrupt sources
  - Pattern (data) match transfer termination
- Multiple DMA channel status interrupts:
  - DMA channel block transfer complete
  - Source empty or half empty
  - Destination full or half full
  - DMA transfer aborted due to an external event
  - Invalid DMA address generated
- DMA debug support features:
  - Most recent address accessed by a DMA channel
  - Most recent DMA channel to transfer data
- CRC Generation module:
  - CRC module can be assigned to any of the available channels
  - CRC module is highly configurable

FIGURE 9-1: DMA BLOCK DIAGRAM



REGISTER 9-14: DCHxSPTR: DMA CHANNEL 'x' SOURCE POINTER REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHSPTR<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHSPTR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHSPTR<15:0>:** Channel Source Pointer bits

1111111111111111 = Points to byte 65,535 of the source
•
•
•
0000000000000001 = Points to byte 1 of the source
0000000000000000 = Points to byte 0 of the source

Note: When in Pattern Detect mode, this register is reset on a pattern detect.

REGISTER 9-15: DCHxDPTR: DMA CHANNEL 'x' DESTINATION POINTER REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHDPTR<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHDPTR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHDPTR<15:0>:** Channel Destination Pointer bits

1111111111111111 = Points to byte 65,535 of the destination
•
•
•
0000000000000001 = Points to byte 1 of the destination
0000000000000000 = Points to byte 0 of the destination

REGISTER 11-4: U1OTGCON: USB OTG CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	DPPULUP	DMPULUP	DPPULDWN	DMPULDWN	VBUSON	OTGEN	VBUSCHG	VBUSDIS

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **DPPULUP:** D+ Pull-Up Enable bit
- 1 = D+ data line pull-up resistor is enabled
- 0 = D+ data line pull-up resistor is disabled

bit 6 **DMPULUP:** D- Pull-Up Enable bit
- 1 = D- data line pull-up resistor is enabled
- 0 = D- data line pull-up resistor is disabled

bit 5 **DPPULDWN:** D+ Pull-Down Enable bit
- 1 = D+ data line pull-down resistor is enabled
- 0 = D+ data line pull-down resistor is disabled

bit 4 **DMPULDWN:** D- Pull-Down Enable bit
- 1 = D- data line pull-down resistor is enabled
- 0 = D- data line pull-down resistor is disabled

bit 3 **VBUSON:** VBUS Power-on bit
- 1 = VBUS line is powered
- 0 = VBUS line is not powered

bit 2 **OTGEN:** OTG Functionality Enable bit
- 1 = DPPULUP, DMPULUP, DPPULDWN and DMPULDWN bits are under software control
- 0 = DPPULUP, DMPULUP, DPPULDWN and DMPULDWN bits are under USB hardware control

bit 1 **VBUSCHG:** VBUS Charge Enable bit
- 1 = VBUS line is charged through a pull-up resistor
- 0 = VBUS line is not charged through a resistor

bit 0 **VBUSDIS:** VBUS Discharge Enable bit
- 1 = VBUS line is discharged through a pull-down resistor
- 0 = VBUS line is not discharged through a resistor

12.1 Parallel I/O (PIO) Ports

All port pins have 10 registers directly associated with their operation as digital I/O. The data direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

12.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx, and TRISx registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than VDD (e.g., 5V) on any desired 5V-tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

See the **"Pin Diagrams"** section for the available pins and their functionality.

12.1.2 CONFIGURING ANALOG AND DIGITAL PORT PINS

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs must have their corresponding ANSEL and TRIS bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

If the TRIS bit is cleared (output) while the ANSELx bit is set, the digital output level (VOH or VOL) is converted by an analog peripheral, such as the ADC module or Comparator module.

When the PORT register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

12.1.3 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP.

12.1.4 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports allows the PIC32MX1XX/2XX 28/44-pin XLP Family devices to generate interrupt requests to the processor in response to a change-of-state on selected input pins. This feature can detect input change-of-states even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a change-of-state.

Five control registers are associated with the CN functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

The CNSTATx register indicates whether a change occurred on the corresponding pin since the last read of the PORTx bit.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups act as a current source or sink source connected to the pin, and eliminate the need for external resistors when push-button or keypad devices are connected. The pull-ups and pull-downs are enabled separately using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note:	Pull-ups and pull-downs on change notification pins should always be disabled when the port pin is configured as a digital output.

An additional control register (CNCONx) is shown in Register 12-3.

12.2 CLR, SET and INV Registers

Every I/O module register has a corresponding CLR (clear), SET (set) and INV (invert) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '0' are not modified.

Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR, or INV register, the base register must be read.

REGISTER 17-1: ICxCON: INPUT CAPTURE 'x' CONTROL REGISTER (CONTINUED)

bit 2-0 **ICM<2:0>:** Input Capture Mode Select bits

111 = Interrupt-Only mode (only supported while in Sleep mode or Idle mode)
110 = Simple Capture Event mode – every edge, specified edge first and every edge thereafter
101 = Prescaled Capture Event mode – every sixteenth rising edge
100 = Prescaled Capture Event mode – every fourth rising edge
011 = Simple Capture Event mode – every rising edge
010 = Simple Capture Event mode – every falling edge
001 = Edge Detect mode – every edge (rising and falling)
000 = Input Capture module is disabled

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

NOTES:

REGISTER 23-4: RTCDATE: RTC DATE VALUE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	YEAR10<3:0>				YEAR01<3:0>			
23:16	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	—	—	—	MONTH10	MONTH01<3:0>			
15:8	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	—	—	DAY10<1:0>		DAY01<3:0>			
7:0	U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
	—	—	—	—	—	WDAY01<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-28 **YEAR10<3:0>:** Binary-Coded Decimal Value of Years bits, 10s place digit; contains a value from 0 to 9

bit 27-24 **YEAR01<3:0>:** Binary-Coded Decimal Value of Years bits, 1s place digit; contains a value from 0 to 9

bit 23-21 **Unimplemented:** Read as '0'

bit 20 **MONTH10:** Binary-Coded Decimal Value of Months bits, 10s place digit; contains a value of 0 or 1

bit 19-16 **MONTH01<3:0>:** Binary-Coded Decimal Value of Months bits, 1s place digit; contains a value from 0 to 9

bit 15-14 **Unimplemented:** Read as '0'

bit 13-12 **DAY10<1:0>:** Binary-Coded Decimal Value of Days bits, 10s place digit; contains a value of 0 to 3

bit 11-8 **DAY01<3:0>:** Binary-Coded Decimal Value of Days bits, 1s place digit; contains a value from 0 to 9

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **WDAY01<2:0>:** Binary-Coded Decimal Value of Weekdays bits; contains a value from 0 to 6

Note: This register is only writable when RTCWREN = 1 (RTCCON<3>).

REGISTER 24-3: AD1CON3: ADC CONTROL REGISTER 3

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ADRC	—	—	SAMC<4:0>(1)				
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W	R/W-0
	ADCS<7:0>(2)							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ADRC:** ADC Conversion Clock Source bit
1 = Clock derived from FRC
0 = Clock derived from Peripheral Bus Clock (PBCLK)

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **SAMC<4:0>:** Auto-Sample Time bits(1)
11111 = 31 TAD
•
•
•
00001 = 1 TAD
00000 = 0 TAD (Not allowed)

bit 7-0 **ADCS<7:0>:** ADC Conversion Clock Select bits(2)
11111111 = TPB • 2 • (ADCS<7:0> + 1) = 512 • TPB = TAD
•
•
•
00000001 = TPB • 2 • (ADCS<7:0> + 1) = 4 • TPB = TAD
00000000 = TPB • 2 • (ADCS<7:0> + 1) = 2 • TPB = TAD

Note 1: This bit is only used if the SSRC<2:0> bits (AD1CON1<7:5>) = 111.
2: This bit is not used if the ADRC (AD1CON3<15>) bit = 1.

NOTES:

REGISTER 27-1: HLVDCON: HIGH/LOW-VOLTAGE DETECT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0	R/W-0
	ON	—	—	—	VDIR(1)	BGVST	—	HLVDET
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	HLVDL<3:0>(1)			

Legend:	HS = Hardware Set	HC = Hardware Cleared	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** HLVD Module Enable bit
1 = HLVD module is enabled
0 = HLVD module is disabled

bit 14-12 **Unimplemented:** Read as '0'

bit 11 **VDIR:** Voltage Change Direction Select bit(1)
1 = Event occurs when voltage equals or exceeds trip point (HLVDL<3:0>)
0 = Event occurs when voltage equals or falls below trip point (HLVDL<3:0>)

bit 10 **BGVST:** Band Gap Reference Voltages Stable Status bit
1 = Indicates internal band gap voltage references is stable
0 = Indicates internal band gap voltage reference is not stable
This bit is readable when the HLVD module is disabled (ON = 0).

bit 9 **Unimplemented:** Read as '0'

bit 8 **HLVDET:** High/Low-Voltage Detection Event Status bit
1 = Indicates HLVD Event interrupt is active
0 = Indicates HLVD Event interrupt is not active

bit 7-4 **Unimplemented:** Read as '0'

Note 1: To avoid false HLVD events, all HLVD module setting changes should occur only when the module is disabled (ON = 0). See Table 33-6 in the **"Electrical Characteristics"** chapter for the actual trip points.

REGISTER 28-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge1 Status bit
Indicates the status of Edge1 and can be written to control edge source
1 = Edge1 has occurred
0 = Edge1 has not occurred

bit 23 **EDG2MOD:** Edge2 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge2 programmed for a positive edge response
0 = Edge2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = C3OUT pin is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as '0'

bit 15 **ON:** ON Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12 **TGEN:** Time Generation Enable bit**(1)**
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 33-42) in **33.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

REGISTER 28-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 10 **EDGSEQEN:** Edge Sequence Enable bit
1 = Edge1 must occur before Edge2 can occur
0 = No edge sequence is needed

bit 9 **IDISSEN:** Analog Current Source Control bit(2)
1 = Analog current source output is grounded
0 = Analog current source output is not grounded

bit 8 **CTTRIG:** Trigger Control bit
1 = Trigger output is enabled
0 = Trigger output is disabled

bit 7-2 **ITRIM<5:0>:** Current Source Trim bits
011111 = Maximum positive change from nominal current
011110
•
•
•
000001 = Minimum positive change from nominal current
000000 = Nominal current output specified by IRNG<1:0>
111111 = Minimum negative change from nominal current
•
•
•
100010
100001 = Maximum negative change from nominal current

bit 1-0 **IRNG<1:0>:** Current Range Select bits(3)
11 = 100 times base current
10 = 10 times base current
01 = Base current level
00 = 1000 times base current(4)

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 33-42) in **33.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

REGISTER 30-4: DEVCFG3: DEVICE CONFIGURATION WORD 3

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	R/P	R/P	R/P	r-1	r-1	r-1	r-1
	—	FUSBIDIO	IOL1WAY	PMDL1WAY	—	—	—	—
23:16	R/P	R/P	r-1	r-1	r-1	r-1	r-1	r-1
	AI2C2	AI2C1	—	—	—	—	—	—
15:8	R/P	R/P	R/P	R/P	R/P	R/P	R/P	R/P
	USERID<15:8>							
7:0	R/P	R/P	R/P	R/P	R/P	R/P	R/P	R/P
	USERID<7:0>							

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **Reserved:** Write '1'

bit 30 **FUSBIDIO:** USB USBID Selection bit
1 = USBID pin is controlled by the USB module
0 = USBID pin is controlled by the port function

bit 29 **IOL1WAY:** Peripheral Pin Select Configuration bit
1 = Allow only one reconfiguration
0 = Allow multiple reconfigurations

bit 28 **PMDI1WAY:** Peripheral Module Disable Configuration bit
1 = Allow only one reconfiguration
0 = Allow multiple reconfigurations

bit 27-24 **Reserved:** Write '1'

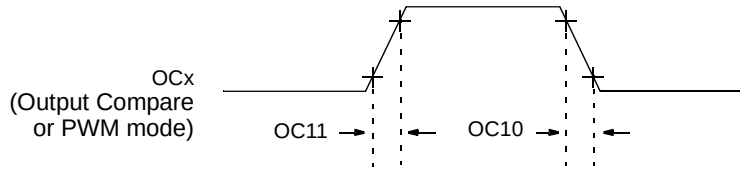
bit 23 **AI2C2:** Alternate I/O Select for I2C2 bit
1 = I2C2 uses the SDA2/SCL2 pins
0 = I2C2 uses the ASDA2/ASCL2 pins

bit 22 **AI2C1:** Alternate I/O Select for I2C1 bit
1 = I2C1 uses the SDA1/SCL1 pins
0 = I2C1 uses the ASDA1/ASCL1 pins

bit 21-16 **Reserved:** Write '1'

bit 15-0 **USERID<15:0>:** User ID bits
This is a 16-bit value that is user-defined and is readable via ICSP™ and JTAG.

FIGURE 33-8: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 33-1 for load conditions.

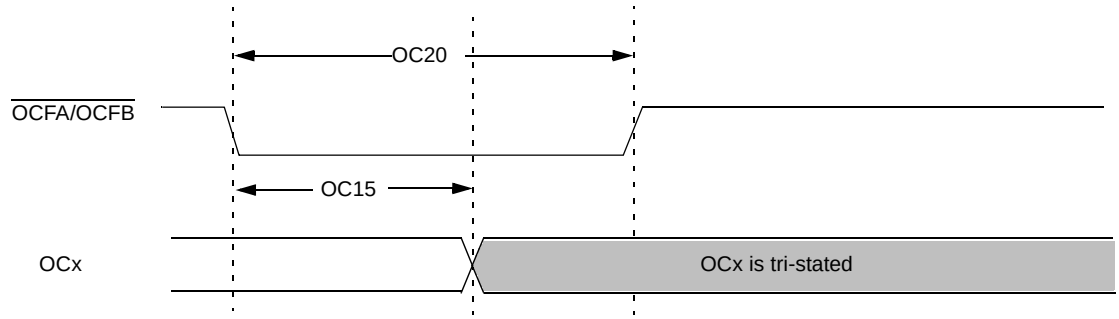
TABLE 33-27: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See parameter DO31

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 33-9: OCx/PWM MODULE TIMING CHARACTERISTICS



Note: Refer to Figure 33-1 for load conditions.

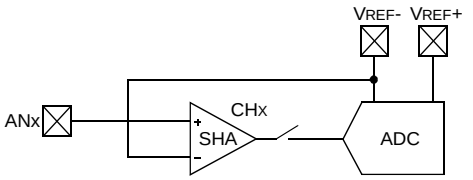
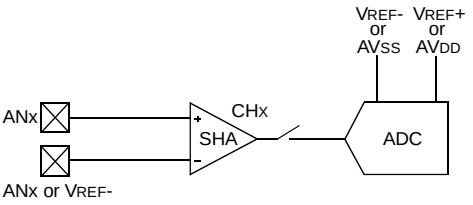
TABLE 33-28: SIMPLE OCx/PWM MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param No.	**Symbol**	**Characteristics(1)**	**Min**	**Typical(2)**	**Max**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWM I/O Change	—	—	50	ns	—
OC20	TFLT	Fault Input Pulse Width	50	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 33-36: 10-BIT CONVERSION RATE PARAMETERS

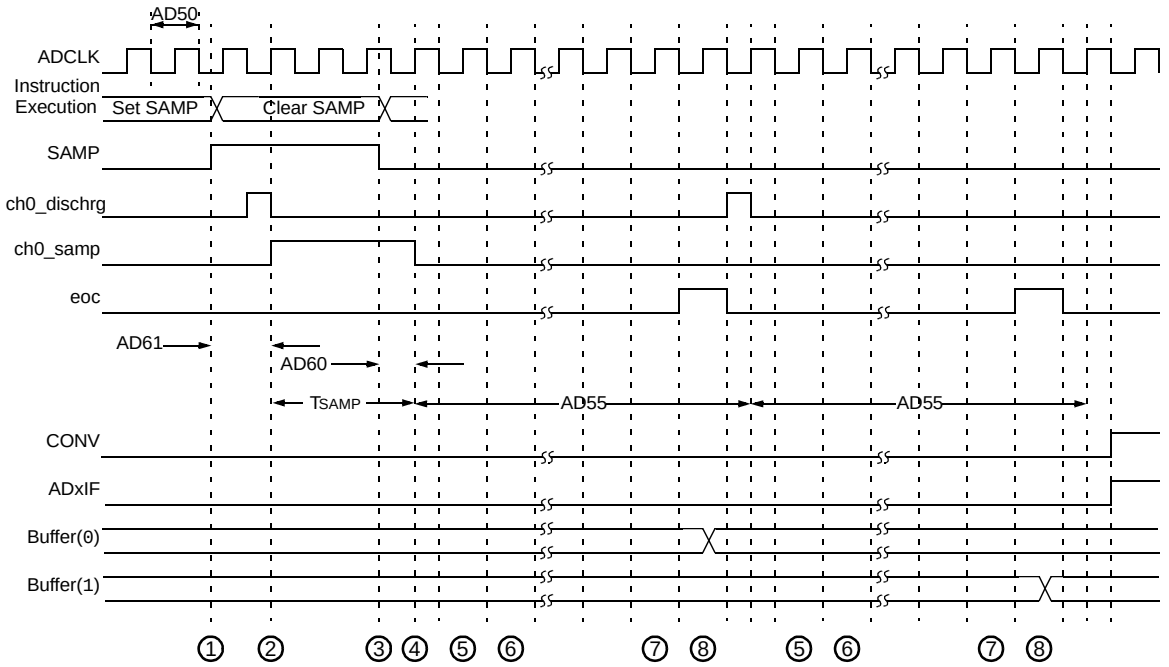
AC CHARACTERISTICS(2)			Standard Operating Conditions: 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
ADC Speed	**TAD Min.**	**Sampling Time Min.**	**RS Max.**	**VDD**	**ADC Channels Configuration**
1 Msps to 400 ksps(1)	65 ns	132 ns	500Ω	3.0V to 3.6V	
Up to 400 ksps	200 ns	200 ns	5.0 kΩ	2.0V to 3.6V	

Note 1: External VREF- and VREF+ pins must be used for correct operation.

2: These parameters are characterized, but not tested in manufacturing.

3: The ADC module is functional at VBORMIN < VDD < 2.0V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

FIGURE 33-18: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 0, SSRC<2:0> = 000)



(1) – Software sets ADxCON. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104) in the *"PIC32 Family Reference Manual"*.

(3) – Software clears ADxCON. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

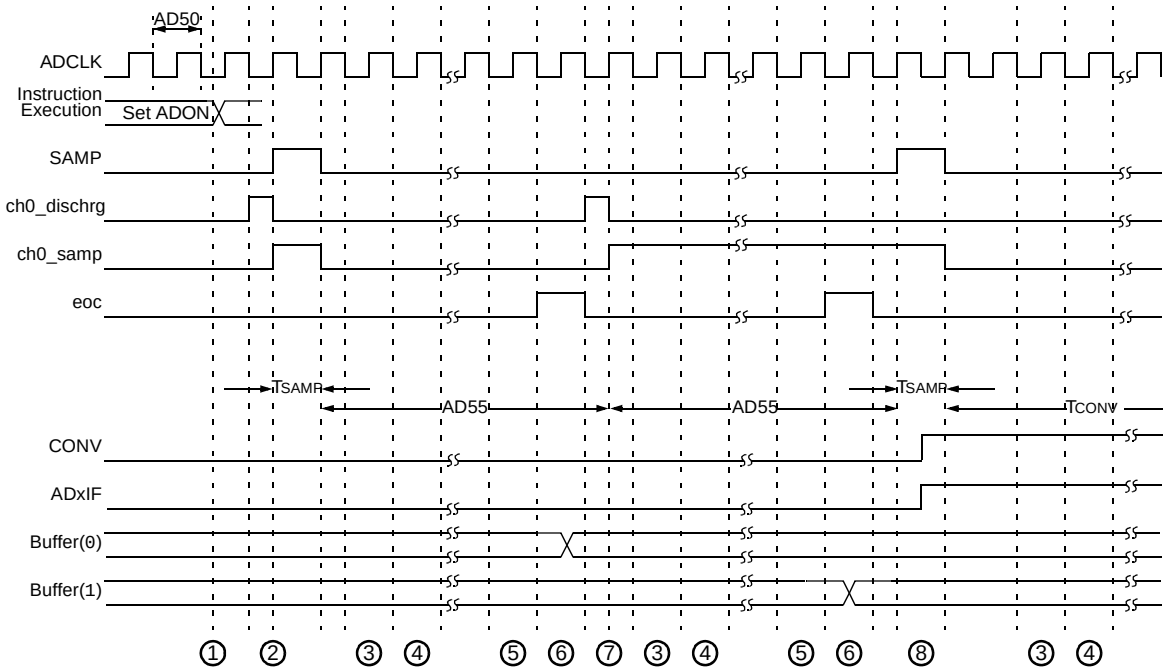
(5) – Convert bit 9.

(6) – Convert bit 8.

(7) – Convert bit 0.

(8) – One TAD for end of conversion.

FIGURE 33-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



1 – Software sets ADxCON. ADON to start AD operation.

2 – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104).

3 – Convert bit 9.

4 – Convert bit 8.

5 – Convert bit 0.

6 – One TAD for end of conversion.

7 – Begin conversion of next channel.

8 – Sample for time specified by SAMC<4:0>.

FIGURE 33-20: PARALLEL SLAVE PORT TIMING